

## FEATURES

- Wide safe operating area
- 10 $\mu$ s short circuit withstand
- Outstanding thermal cycling capability
- Co-pack configuration
- High tolerance of non-uniform clamping pressure

## APPLICATIONS

- High voltage DC transmission
- Flexible AC transmission systems
- High reliability inverters
- Motor controllers

## ORDERING INFORMATION

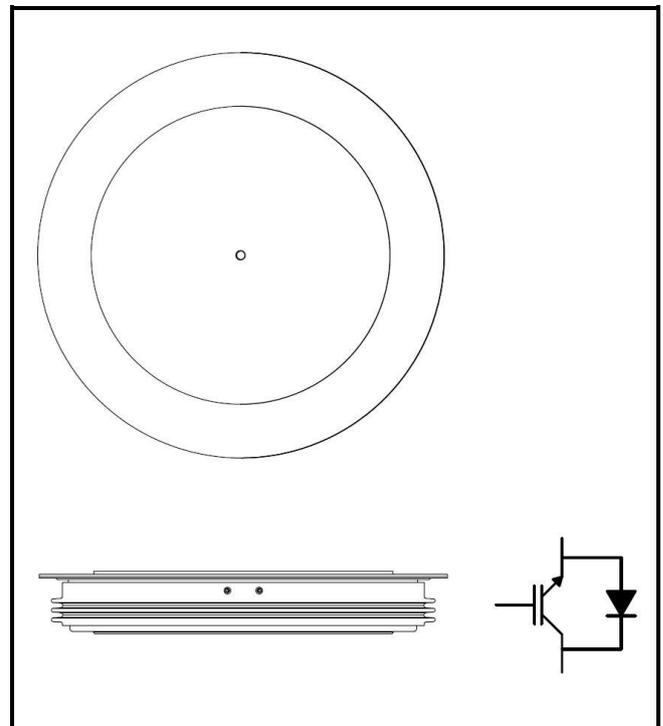
Order As:

DPI1200P45C2626

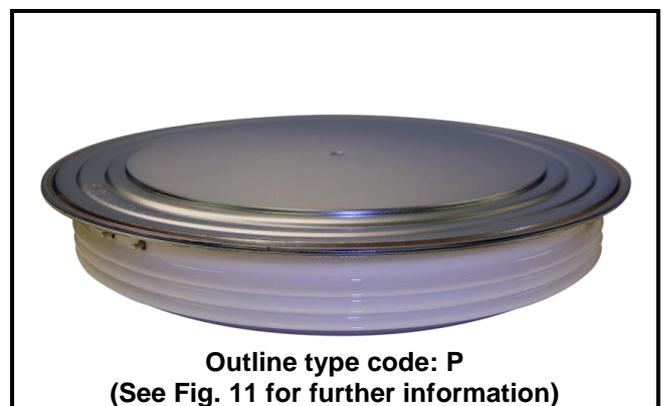
Note: When ordering, please use the complete part number

## KEY PARAMETERS

$V_{CES}$		<b>4500V</b>
$V_{CE(sat)}$	<b>(typ)</b>	<b>2.6V</b>
$I_C$	<b>(max)</b>	<b>1200A</b>
$I_{C(PK)}$	<b>(max)</b>	<b>2400A</b>



**Fig.1 Circuit configuration**



**Outline type code: P**  
**(See Fig. 11 for further information)**

**Fig. 2 Package**

## ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{case} = 25^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
$V_{CES}$	Collector-emitter voltage	$V_{GE} = 0\text{V}$	4500	V
$V_{GES}$	Gate-emitter voltage	-	$\pm 20$	V
$I_C$	Continuous collector current	$T_{case} = 90^{\circ}\text{C}$	1200	A
$I_{C(PK)}$	Peak collector current	1ms, $T_j = 125^{\circ}\text{C}$	2400	A
$P_{max}$	Max. transistor power dissipation	$T_{case} = 25^{\circ}\text{C}$ , $T_j = 125^{\circ}\text{C}$	11.4	kW
$I_{FSM}$	Surge (non-repetitive) on-state current	10ms half-sine, $T_{case}=125^{\circ}\text{C}$ , $V_R=0\text{V}$	20.4	kA

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
$R_{th(j-c)}$ *	Thermal resistance – junction to case IGBT (collector side)	DC	-	0.0088	$^{\circ}\text{C/W}$
$R_{th(j-c)}$ *	Thermal resistance – junction to case Diode (cathode side)	DC	-	0.0088	$^{\circ}\text{C/W}$
$R_{th(c-h)}$ *	Thermal resistance – case to heatsink IGBT (collector side)	Clamping force 70kN (with mounting compound)	-	0.0036	$^{\circ}\text{C/W}$
$R_{th(c-h)}$ *	Thermal resistance – case to heatsink Diode (cathode side)	Clamping force 70kN (with mounting compound)	-	0.0036	$^{\circ}\text{C/W}$
$T_{vj}$	Virtual junction temperature	Transistor	-	125	$^{\circ}\text{C}$
		Diode	-	125	$^{\circ}\text{C}$
$T_{stg}$	Storage temperature range	-	-40	125	$^{\circ}\text{C}$
$F_m$	Clamping force	-	65	75	kN

**Note:**

\* Device should be cooled from collector/cathode side only.

**ELECTRICAL CHARACTERISTICS**
**T<sub>case</sub> = 25°C unless stated otherwise.**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I <sub>CES</sub>	Collector cut-off current	V <sub>GE</sub> = 0V, V <sub>CE</sub> = V <sub>CES</sub>			5	mA
		V <sub>GE</sub> = 0V, V <sub>CE</sub> = V <sub>CES</sub> , T <sub>case</sub> = 125°C		25	75	mA
I <sub>GES</sub>	Gate leakage current	V <sub>GE</sub> = ± 20V, V <sub>CE</sub> = 0V			10	μA
V <sub>GE(TH)</sub>	Gate threshold voltage	I <sub>C</sub> = 130mA, V <sub>GE</sub> = V <sub>CE</sub>		6.1		V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 1200A, T <sub>j</sub> = 25°C		2.6		V
		V <sub>GE</sub> = 15V, I <sub>C</sub> = 1200A, T <sub>j</sub> = 125°C		3.0		V
I <sub>F</sub>	Diode forward current	DC		1200		A
I <sub>FM</sub>	Diode maximum forward current	t <sub>p</sub> = 1ms		2400		A
V <sub>F</sub>	Diode forward voltage	I <sub>F</sub> = 1200A, T <sub>j</sub> = 25°C		2.3		V
		I <sub>F</sub> = 1200A, T <sub>j</sub> = 125°C		2.4		V
Q <sub>g</sub>	Gate charge	±15V		19		μC
SC <sub>Data</sub>	Short circuit current, I <sub>SC</sub>	T <sub>j</sub> = 125°C, V <sub>CC</sub> = 3400V t <sub>p</sub> ≤ 10μs, V <sub>GE</sub> ≤ 15V V <sub>CE(max)</sub> = V <sub>CES</sub> - L* x di/dt IEC 60747-9		5000		A

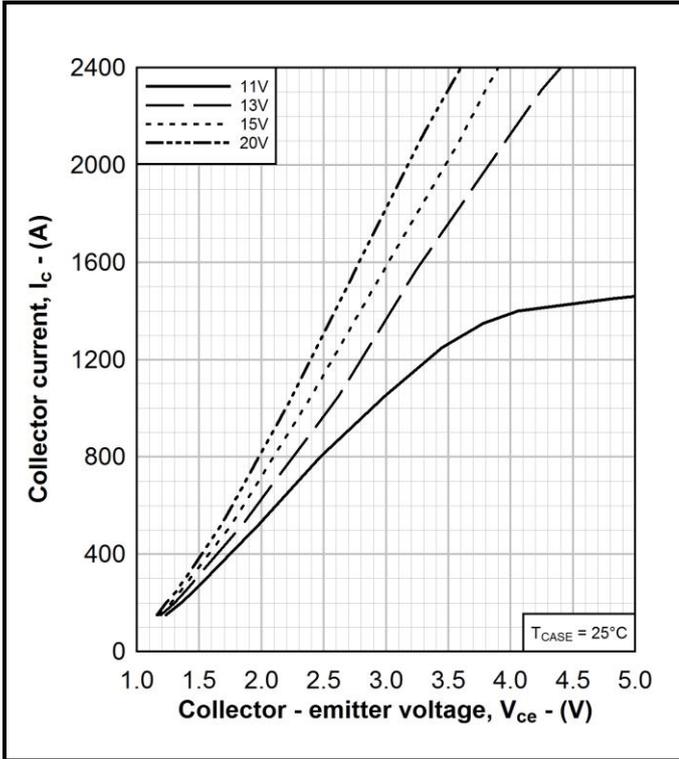
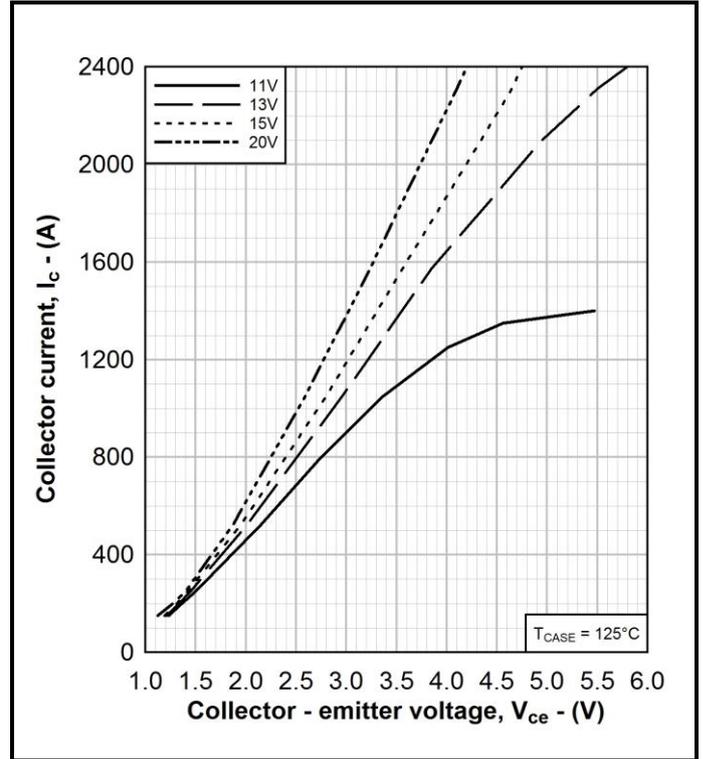
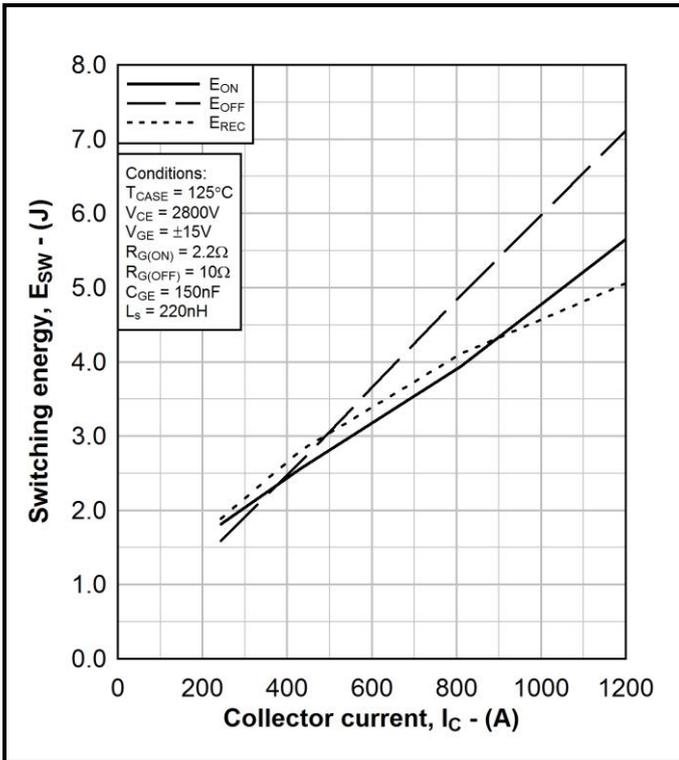
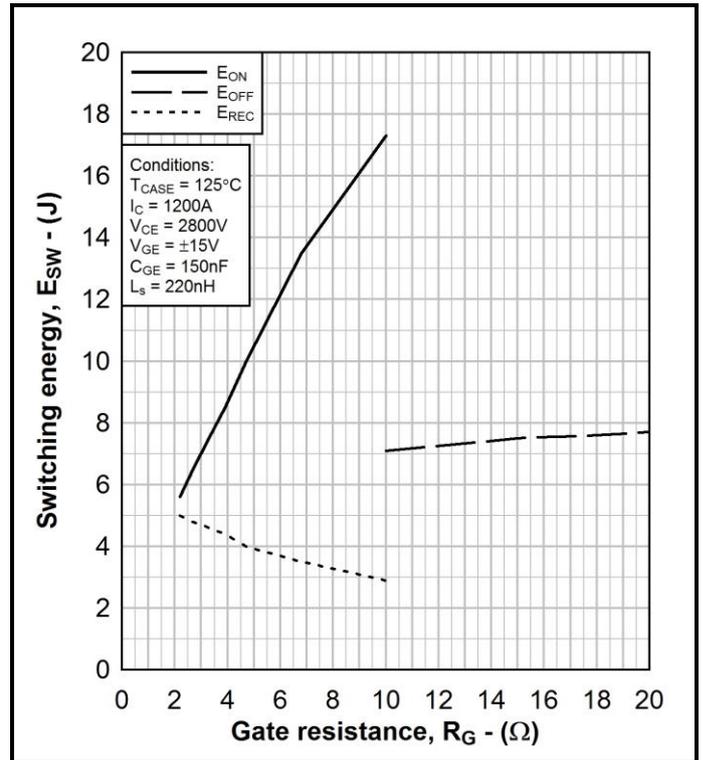
**Note:**

\* L is the circuit inductance

## ELECTRICAL CHARACTERISTICS

$T_{\text{case}} = 125^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
$t_{d(\text{off})}$	Turn-off delay time	$I_C = 1200\text{A}$ $V_{GE} = \pm 15\text{V}$ $V_{CE} = 2800\text{V}$ $R_{G(\text{ON})} = 2.2\Omega$ $R_{G(\text{OFF})} = 10\Omega$ $C_{GE} = 150\text{nF}$ $L_S \sim 220\text{nH}$		4800		ns
$t_f$	Fall time			2900		ns
$E_{\text{OFF}}$	Turn-off energy loss			7000		mJ
$t_{d(\text{on})}$	Turn-on delay time			400		ns
$t_r$	Rise time			400		ns
$E_{\text{ON}}$	Turn-on energy loss			5600		mJ
$Q_{rr}$	Diode reverse recovery charge	$I_F = 1200\text{A}$ $V_{CE} = 2800\text{V}$ $dI_F/dt = 3500\text{A}/\mu\text{s}$		2700		$\mu\text{C}$
$I_{rr}$	Diode reverse recovery current			1800		A
$E_{\text{rec}}$	Diode reverse recovery energy			5000		mJ


**Fig. 3 Typical output characteristics**

**Fig. 4 Typical output characteristics**

**Fig. 5 Typical switching energy vs. collector current**

**Fig. 6 Typical switching energy vs. gate resistance**

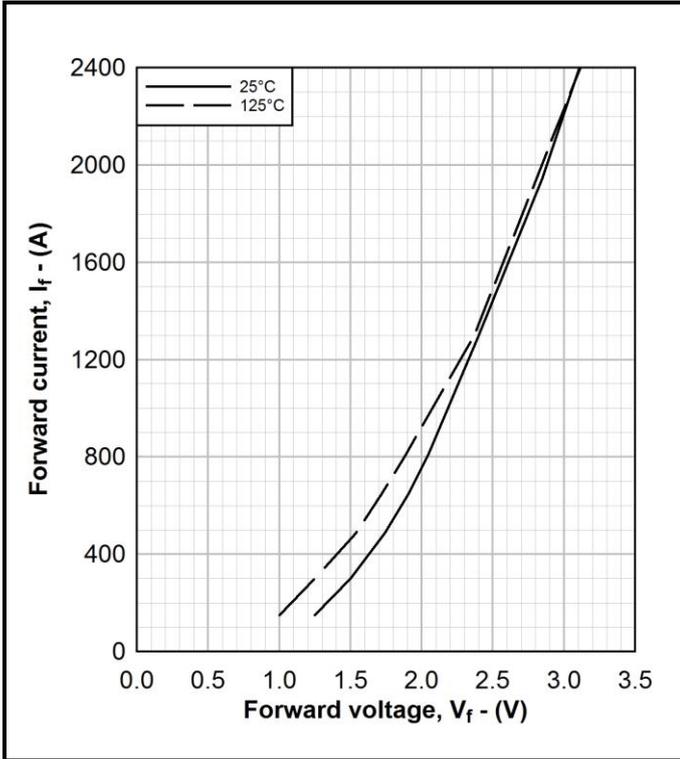


Fig. 7 Diode typical forward characteristics

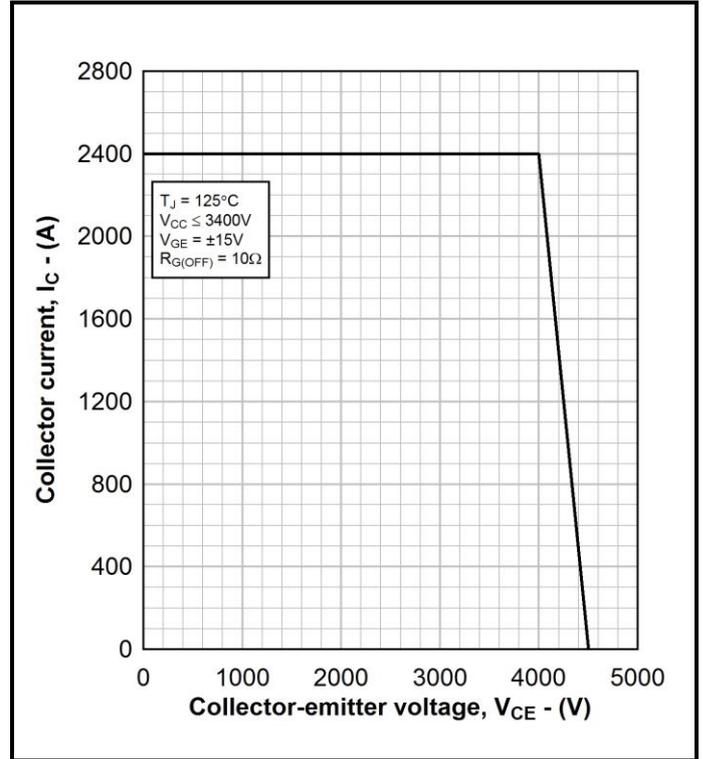


Fig. 8 Reverse bias safe operating area

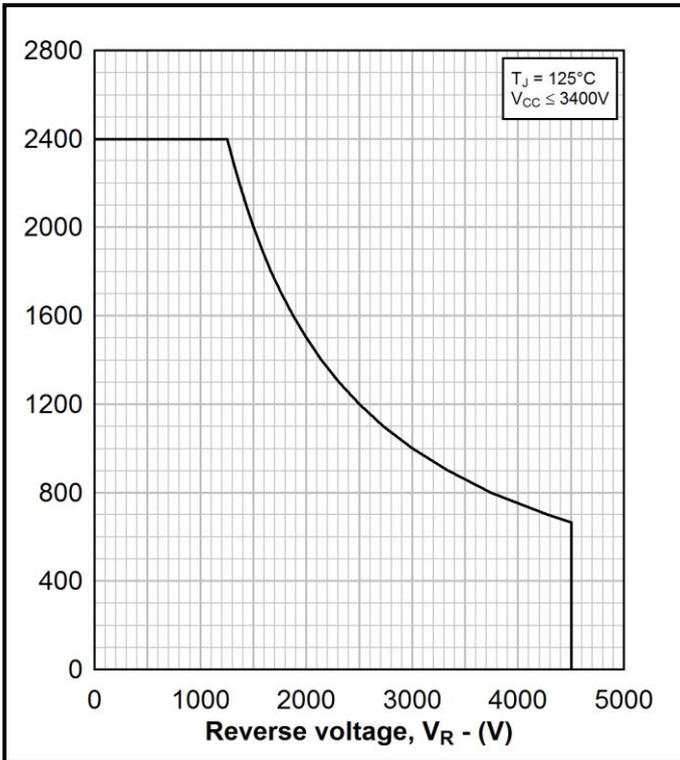


Fig. 9 Diode reverse bias safe operating area

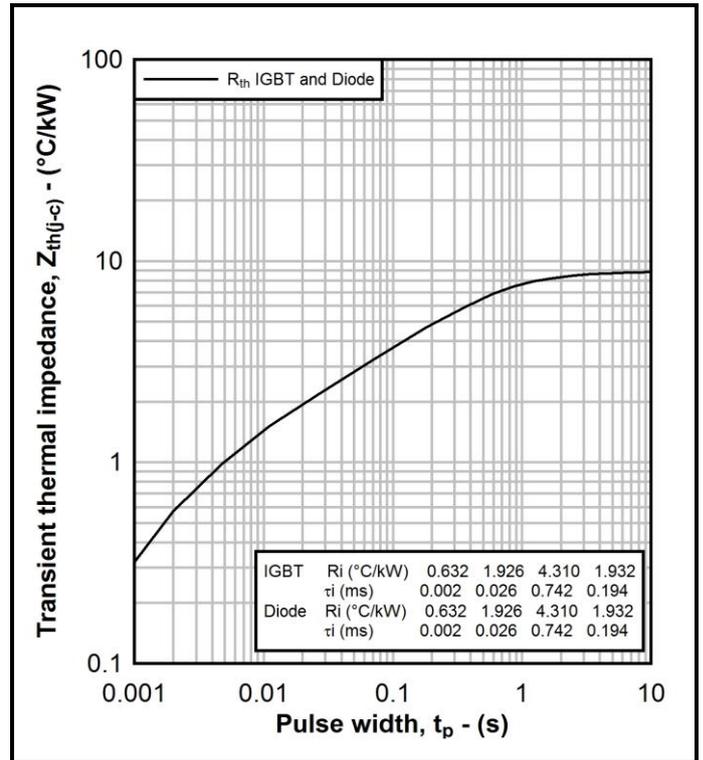
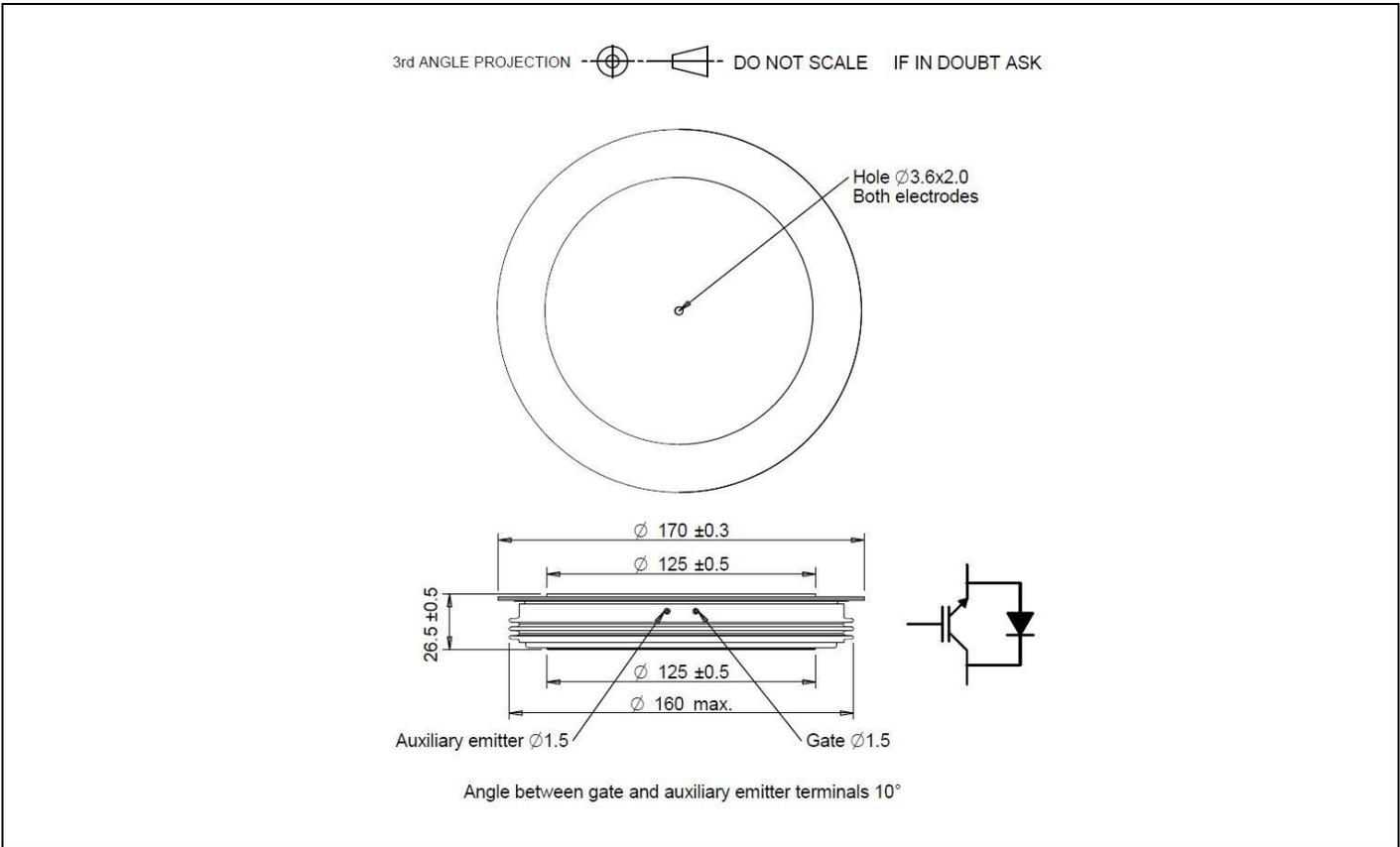


Fig. 10 Transient thermal impedance

**PACKAGE DETAILS**

For further package information, please visit our website or contact Customer Services.  
 All dimensions in mm, unless stated otherwise.  
**DO NOT SCALE.**



**Fig. 11 Package outline**

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